

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t1785cn8#pbf

(Engineering Calculation)

PDIP

(printed on: 2020-07-11 20:17:21)

TOTAL MASS (g) : 0.502241

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.004656 | 1000000 | 9270.44433594 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.149760 | 975000 | 298183.34375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.003686 | 24000 | 7339.10107422 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000046 | 300 | 91.5894393921 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000108 | 700 | 215.036071777 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.153600 | 1000000 | 305829.09375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.012410 | 1000000 | 24709.8164062 | | |
| | | External Plating Total: | | | | 0.012410 | 1000000 | 24709.8164062 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001228 | 1000000 | 2445.03979492 | | |
| Internal Plating Total: | | | | 0.001228 | 1000000 | 2445.03979492 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001246 | 750000 | 2480.87915039 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000415 | 250000 | 826.295959473 | | |
| Die Attach Total: | | | | 0.001661 | 1000000 | 3307.17504883 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.044334 | 135000 | 88272.3125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.282424 | 860000 | 562327.3125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.001642 | 5000 | 3269.34472656 | | |
| | | Encapsulation Total: | | | | 0.328400 | 1000000 | 653868.9375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000286 | 1000000 | 569.44732666 | | |
| | | | | | TOTAL MASS (g) : | 0.502241 | | |